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Details

Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	I ² C, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	16
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	20-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s9s08el32f1mtj

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Chapter 2 Pins and Connections

2.2 Recommended System Connections

Figure 2-3 shows pin connections that are common to MC9S08EL32 Series and MC9S08SL16 Series application systems.



Figure 2-3. Basic System Connections

2.2.1 Power

 V_{DD} and V_{SS} are the primary power supply pins for the MCU. This voltage source supplies power to all I/O buffer circuitry and to an internal voltage regulator. The internal voltage regulator provides a regulated lower-voltage source to the CPU and other internal circuitry of the MCU.

Typically, application systems have two separate capacitors across the power pins. In this case, there should be a bulk electrolytic capacitor, such as a $10-\mu$ F tantalum capacitor, to provide bulk charge storage for the overall system and a $0.1-\mu$ F ceramic bypass capacitor located as near to the MCU power pins as practical to suppress high-frequency noise. Each pin must have a bypass capacitor for best noise suppression.

 V_{DDA} and V_{SSA} are the analog power supply pins for the MCU. This voltage source supplies power to the ADC module. A 0.1- μ F ceramic bypass capacitor should be located as near to the MCU power pins as practical to suppress high-frequency noise. The V_{REFH} and V_{REFL} pins are the voltage reference high and voltage reference low inputs, respectively, for the ADC module.



Figure 4-2. Program and Erase Flowchart

4.5.4 Burst Program Execution

The burst program command is used to program sequential bytes of data in less time than would be required using the standard program command. This is possible because the high voltage to the FLASH array does not need to be disabled between program operations. Ordinarily, when a program or erase command is issued, an internal charge pump associated with the FLASH memory must be enabled to supply high voltage to the array. Upon completion of the command, the charge pump is turned off. When a burst program command is issued, the charge pump is enabled and then remains enabled after completion of the burst program operation if these two conditions are met:

- The next burst program command has been queued before the current program operation has completed.
- The next sequential address selects a byte on the same burst block as the current byte being programmed. A burst block in this FLASH memory consists of 64 bytes. A new burst block begins at each 64-byte address boundary.



Chapter 4 Memory

NOTE

The FCBEF flag will not set after launching the sector erase abort command. If an attempt is made to start a new command write sequence with a sector erase abort operation active, the FACCERR flag in the FSTAT register will be set. A new command write sequence may be started after clearing the ACCERR flag, if set.

NOTE

The sector erase abort command should be used sparingly since a sector erase operation that is aborted counts as a complete program/erase cycle.

4.5.6 Access Errors

An access error occurs whenever the command execution protocol is violated.

Any of the following specific actions will cause the access error flag (FACCERR) in FSTAT to be set. FACCERR must be cleared by writing a 1 to FACCERR in FSTAT before any command can be processed.

- Writing to a FLASH address before the internal FLASH and EEPROM clock frequency has been set by writing to the FCDIV register.
- Writing to a FLASH address while FCBEF is not set. (A new command cannot be started until the command buffer is empty.)
- Writing a second time to a FLASH address before launching the previous command. (There is only one write to FLASH for every command.)
- Writing a second time to FCMD before launching the previous command. (There is only one write to FCMD for every command.)
- Writing to any FLASH control register other than FCMD after writing to a FLASH address.
- Writing any command code other than the six allowed codes (0x05, 0x20, 0x25, 0x40, 0x41, or 0x47) to FCMD.
- Writing any FLASH control register other than to write to FSTAT (to clear FCBEF and launch the command) after writing the command to FCMD.
- The MCU enters stop mode while a program or erase command is in progress. (The command is aborted.)
- Writing the byte program, burst program, sector erase or sector erase abort command code (0x20, 0x25, 0x40, or 0x47) with a background debug command while the MCU is secured. (The background debug controller can do blank check and mass erase commands only when the MCU is secure.)
- Writing 0 to FCBEF to cancel a partial command.



Source	Operation	dress lode	Object Code	/cles	Cyc-by-Cyc	Affect on CCR		
		PA		ΰ	Dotano	V 1 1 H	INZC	
BLE rel	Branch if Less Than or Equal To (if Z (N \oplus V) = 1) (Signed)	REL	93 rr	3	qqq	-11-		
BLO rel	Branch if Lower (if $C = 1$) (Same as BCS)	REL	25 rr	3	qqq	-11-		
BLS rel	Branch if Lower or Same (if $C \mid Z = 1$)	REL	23 rr	3	ppp	-11-		
BLT rel	Branch if Less Than (if $N \oplus V = 1$) (Signed)	REL	91 rr	3	ррр	-11-		
BMC rel	Branch if Interrupt Mask Clear (if I = 0)	REL	2C rr	3	ррр	-11-		
BMI rel	Branch if Minus (if N = 1)	REL	2B rr	3	ррр	-11-		
BMS rel	Branch if Interrupt Mask Set (if I = 1)	REL	2D rr	3	ррр	-11-		
BNE rel	Branch if Not Equal (if Z = 0)	REL	26 rr	3	ррр	-11-		
BPL rel	Branch if Plus (if N = 0)	REL	2A rr	3	ррр	-11-		
BRA rel	Branch Always (if I = 1)	REL	20 rr	3	ррр	-11-		
BRCLR n,opr8a,rel	Branch if Bit <i>n</i> in Memory Clear (if (Mn) = 0)	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	01 dd rr 03 dd rr 05 dd rr 07 dd rr 09 dd rr 0B dd rr 0D dd rr 0F dd rr	5 5 5 5 5 5 5 5 5 5	rpppp rpppp rpppp rpppp rpppp rpppp rpppp	- 1 1 -	t	
BRN rel	Branch Never (if I = 0)	REL	21 rr	3	ррр	-11-		
BRSET n,opr8a,rel	Branch if Bit <i>n</i> in Memory Set (if (Mn) = 1)	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	00 dd rr 02 dd rr 04 dd rr 06 dd rr 08 dd rr 0A dd rr 0C dd rr 0E dd rr	5 5 5 5 5 5 5 5 5	rpppp rpppp rpppp rpppp rpppp rpppp rpppp rpppp	-11-	t	
BSET n,opr8a	Set Bit <i>n</i> in Memory (Mn ← 1)	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	10 dd 12 dd 14 dd 16 dd 18 dd 1A dd 1C dd 1E dd	5 5 5 5 5 5 5 5 5 5	rfwpp rfwpp rfwpp rfwpp rfwpp rfwpp rfwpp rfwpp	- 1 1 -		
BSR rel	Branch to Subroutine $PC \leftarrow (PC) + \$0002$ push (PCL); $SP \leftarrow (SP) - \$0001$ push (PCH); $SP \leftarrow (SP) - \$0001$ $PC \leftarrow (PC) + rel$	REL	AD rr	5	ssppp	-11-		
CBEQ opr8a,rel CBEQA #opr8i,rel CBEQX #opr8i,rel CBEQ oprx8,X+,rel CBEQ ,X+,rel CBEQ oprx8,SP,rel	Compare and Branch if $(A) = (M)$ Branch if $(A) = (M)$ Branch if $(X) = (M)$ Branch if $(A) = (M)$ Branch if $(A) = (M)$ Branch if $(A) = (M)$	DIR IMM IX1+ IX+ SP1	31 dd rr 41 ii rr 51 ii rr 61 ff rr 71 rr 9E 61 ff rr	5 4 5 5 6	rpppp pppp rppp rfppp rfppp prpppp	- 1 1 -		

Table 7-2. Instruction Set Summary (Sheet 3 of 9)

MC9S08EL32 Series and MC9S08SL16 Series Data Sheet, Rev. 3



Chapter 10 Analog-to-Digital Converter (S08ADCV1)

10.1.2 Alternate Clock

The ADC module is capable of performing conversions using the MCU bus clock, the bus clock divided by two, the local asynchronous clock (ADACK) within the module, or the alternate clock, ALTCLK. The alternate clock for the MC9S08EL32 Series and MC9S08SL16 Series MCU devices is the external reference clock (ICSERCLK).

The selected clock source must run at a frequency such that the ADC conversion clock (ADCK) runs at a frequency within its specified range (f_{ADCK}) after being divided down from the ALTCLK input as determined by the ADIV bits.

ALTCLK is active while the MCU is in wait mode provided the conditions described above are met. This allows ALTCLK to be used as the conversion clock source for the ADC while the MCU is in wait mode.

ALTCLK cannot be used as the ADC conversion clock source while the MCU is in either stop2 or stop3.

10.1.3 Hardware Trigger

The ADC hardware trigger, ADHWT, is the output from the real time counter (RTC) overflow. The RTC can be configured to cause a hardware trigger in MCU run, wait, and stop3 modes.

10.1.4 Temperature Sensor

The ADC module includes a temperature sensor whose output is connected to AD26. Equation 10-1 provides an approximate transfer function of the temperature sensor.

where:

- V_{TEMP} is the voltage of the temperature sensor channel at the ambient temperature.

— V_{TEMP25} is the voltage of the temperature sensor channel at 25°C.

— m is the hot or cold voltage versus temperature slope in $V/^{\circ}C$.

For temperature calculations, use the V_{TEMP25} and m values from the ADC Electricals table.

In application code, the user reads the temperature sensor channel, calculates V_{TEMP} , and compares to V_{TEMP25} . If V_{TEMP} is greater than V_{TEMP25} the cold slope value is applied in Equation 10-1. If V_{TEMP} is less than V_{TEMP25} the hot slope value is applied in Equation 10-1.

Analog-to-Digital Converter (S08ADC10V1)

- 2. Update status and control register 2 (ADCSC2) to select the conversion trigger (hardware or software) and compare function options, if enabled.
- 3. Update status and control register 1 (ADCSC1) to select whether conversions will be continuous or completed only once, and to enable or disable conversion complete interrupts. The input channel on which conversions will be performed is also selected here.

10.5.1.2 Pseudo — Code Example

In this example, the ADC module will be set up with interrupts enabled to perform a single 10-bit conversion at low power with a long sample time on input channel 1, where the internal ADCK clock will be derived from the bus clock divided by 1.

ADCCFG = 0x98 (%10011000)

Bit 7	ADLPC	1	Configures for low power (lowers maximum clock speed)
Bit 6:5	ADIV	00	Sets the ADCK to the input clock \div 1
Bit 4	ADLSMP	1	Configures for long sample time
Bit 3:2	MODE	10	Sets mode at 10-bit conversions
Bit 1:0	ADICLK	00	Selects bus clock as input clock source

ADCSC2 = 0x00 (%00000000)

Bit 7	ADACT	0	Flag indicates if a conversion is in progress
Bit 6	ADTRG	0	Software trigger selected
Bit 5	ACFE	0	Compare function disabled
Bit 4	ACFGT	0	Not used in this example
Bit 3:2		00	Unimplemented or reserved, always reads zero
Bit 1:0		00	Reserved for Freescale's internal use; always write zero

ADCSC1 = 0x41 (%01000001)

Bit 7	COCO	0	Read-only flag which is set when a conversion completes
Bit 6	AIEN	1	Conversion complete interrupt enabled
Bit 5	ADCO	0	One conversion only (continuous conversions disabled)
Bit 4:0	ADCH	00001	Input channel 1 selected as ADC input channel

ADCRH/L = 0xxx

Holds results of conversion. Read high byte (ADCRH) before low byte (ADCRL) so that conversion data cannot be overwritten with data from the next conversion.

ADCCVH/L = 0xxx

Holds compare value when compare function enabled

APCTL1=0x02

AD1 pin I/O control disabled. All other AD pins remain general purpose I/O pins

APCTL2=0x00

All other AD pins remain general purpose I/O pins



Inter-Integrated Circuit (S08IICV2)

Refer to the direct-page register summary in the memory chapter of this document for the absolute address assignments for all IIC registers. This section refers to registers and control bits only by their names. A Freescale-provided equate or header file is used to translate these names into the appropriate absolute addresses.

11.3.1 IIC Address Register (IICA)



Figure 11-3. IIC Address Register (IICA)

Table 11-2. IICA Field Descriptions

Field	Description
7–1 AD[7:1]	Slave Address. The AD[7:1] field contains the slave address to be used by the IIC module. This field is used on the 7-bit address scheme and the lower seven bits of the 10-bit address scheme.

11.3.2 IIC Frequency Divider Register (IICF)



Figure 11-4. IIC Frequency Divider Register (IICF)



11.4 Functional Description

This section provides a complete functional description of the IIC module.

11.4.1 IIC Protocol

The IIC bus system uses a serial data line (SDA) and a serial clock line (SCL) for data transfer. All devices connected to it must have open drain or open collector outputs. A logic AND function is exercised on both lines with external pull-up resistors. The value of these resistors is system dependent.

Normally, a standard communication is composed of four parts:

- Start signal
- Slave address transmission
- Data transfer
- Stop signal

The stop signal should not be confused with the CPU stop instruction. The IIC bus system communication is described briefly in the following sections and illustrated in Figure 11-9.



Figure 11-9. IIC Bus Transmission Signals

11.4.1.1 Start Signal

When the bus is free, no master device is engaging the bus (SCL and SDA lines are at logical high), a master may initiate communication by sending a start signal. As shown in Figure 11-9, a start signal is defined as a high-to-low transition of SDA while SCL is high. This signal denotes the beginning of a new data transfer (each data transfer may contain several bytes of data) and brings all slaves out of their idle states.



After a repeated start condition (Sr), all other slave devices also compare the first seven bits of the first byte of the slave address with their own addresses and test the eighth (R/\overline{W}) bit. However, none of them are addressed because $R/\overline{W} = 1$ (for 10-bit devices) or the 11110XX slave address (for 7-bit devices) does not match.

s	Slave Address 1st 7 bits	R/W	A1	Slave Address 2nd byte	A2	Sr	Slave Address 1st 7 bits	R/W	A3	Data	A	 Data	А	Р
	11110 + AD10 + AD9	0		AD[8:1]			11110 + AD10 + AD9	1						

 Table 11-11. Master-Receiver Addresses a Slave-Transmitter with a 10-bit Address

After the master-receiver has sent the first byte of the 10-bit address, the slave-transmitter sees an IIC interrupt. Software must ensure the contents of IICD are ignored and not treated as valid data for this interrupt.

11.4.3 General Call Address

General calls can be requested in 7-bit address or 10-bit address. If the GCAEN bit is set, the IIC matches the general call address as well as its own slave address. When the IIC responds to a general call, it acts as a slave-receiver and the IAAS bit is set after the address cycle. Software must read the IICD register after the first byte transfer to determine whether the address matches is its own slave address or a general call. If the value is 00, the match is a general call. If the GCAEN bit is clear, the IIC ignores any data supplied from a general call address by not issuing an acknowledgement.

11.5 Resets

The IIC is disabled after reset. The IIC cannot cause an MCU reset.

11.6 Interrupts

The IIC generates a single interrupt.

An interrupt from the IIC is generated when any of the events in Table 11-12 occur, provided the IICIE bit is set. The interrupt is driven by bit IICIF (of the IIC status register) and masked with bit IICIE (of the IIC control register). The IICIF bit must be cleared by software by writing a 1 to it in the interrupt routine. You can determine the interrupt type by reading the status register.

Interrupt Source	Status	Flag	Local Enable
Complete 1-byte transfer	TCF	IICIF	IICIE
Match of received calling address	IAAS	IICIF	IICIE
Arbitration Lost	ARBL	IICIF	IICIE

Table 11-12. Interrupt Summary

11.6.1 Byte Transfer Interrupt

The TCF (transfer complete flag) bit is set at the falling edge of the ninth clock to indicate the completion of byte transfer.



Inter-Integrated Circuit (S08IICV2)



NOTES:

- 1. If general call is enabled, a check must be done to determine whether the received address was a general call address (0x00). If the received address was a general call address, then the general call must be handled by user software.
- 2. When 10-bit addressing is used to address a slave, the slave sees an interrupt following the first byte of the extended address. User software must ensure that for this interrupt, the contents of IICD are ignored and not treated as a valid data transfer

Figure 11-12. Typical IIC Interrupt Routine

MC9S08EL32 Series and MC9S08SL16 Series Data Sheet, Rev. 3



Chapter 12 Slave LIN Interface Controller (S08SLICV1)

12.1 Introduction

The slave LIN interface controller (SLIC) is designed to provide slave node connectivity on a local interconnect network (LIN) sub-bus. LIN is an open-standard serial protocol developed for the automotive industry to connect sensors, motors, and actuators.



This means an extra step is taken inside the interrupt service routine after the identifier has been decoded and is determined to be an ID for a request message frame.

Figure 12-16 deals with request messages, where the SLIC will be transmitting data to the master node. If the received identifier corresponds to a standard LIN command frame (i.e., 1-8 data bytes), the message processing is very simple. The user must load the data to be transmitted into the transmit buffer by writing it to the SLCD registers. The first byte to be transmitted on the LIN bus must be loaded into SLCD0, then SLCD1 for the second byte, etc. After all of the bytes to be transmitted are loaded in this way, a single write to SLCDLC will allow the user to encode the number of data bytes to be transmitted (1–8 bytes for standard request frames), set the proper checksum calculation method for the data (CHKMOD), as well as signal the SLIC that the buffer is ready by writing a 1 to TXGO. TXGO will remain set to 1 until the buffer is sent successfully or an error is encountered, signaling to the application code that the buffer is in process of transmitting. In cases of 1–8 data bytes only being sent (standard LIN request frames), the SLIC automatically calculates and transmits the checksum byte at the end of the message frame. The user can exit the ISR after SLCDLC has been written and the SLCF flag has been cleared.



Serial Peripheral Interface (S08SPIV3)

The most common uses of the SPI system include connecting simple shift registers for adding input or output ports or connecting small peripheral devices such as serial A/D or D/A converters. Although Figure 13-2 shows a system where data is exchanged between two MCUs, many practical systems involve simpler connections where data is unidirectionally transferred from the master MCU to a slave or from a slave to the master MCU.

13.1.2.2 SPI Module Block Diagram

Figure 13-3 is a block diagram of the SPI module. The central element of the SPI is the SPI shift register. Data is written to the double-buffered transmitter (write to SPID) and gets transferred to the SPI shift register at the start of a data transfer. After shifting in a byte of data, the data is transferred into the double-buffered receiver where it can be read (read from SPID). Pin multiplexing logic controls connections between MCU pins and the SPI module.

When the SPI is configured as a master, the clock output is routed to the SPSCK pin, the shifter output is routed to MOSI, and the shifter input is routed from the MISO pin.

When the SPI is configured as a slave, the SPSCK pin is routed to the clock input of the SPI, the shifter output is routed to MISO, and the shifter input is routed from the MOSI pin.

In the external SPI system, simply connect all SPSCK pins to each other, all MISO pins together, and all MOSI pins together. Peripheral devices often use slightly different names for these pins.





14.1.1 Features

Features of SCI module include:

- Full-duplex, standard non-return-to-zero (NRZ) format
- Double-buffered transmitter and receiver with separate enables
- Programmable baud rates (13-bit modulo divider)
- Interrupt-driven or polled operation:
 - Transmit data register empty and transmission complete
 - Receive data register full
 - Receive overrun, parity error, framing error, and noise error
 - Idle receiver detect
 - Active edge on receive pin
 - Break detect supporting LIN
- Hardware parity generation and checking
- Programmable 8-bit or 9-bit character length
- Receiver wakeup by idle-line or address-mark
- Optional 13-bit break character generation / 11-bit break character detection
- Selectable transmitter output polarity

14.1.2 Modes of Operation

See Section 14.3, "Functional Description," For details concerning SCI operation in these modes:

- 8- and 9-bit data modes
- Stop mode operation
- Loop mode
- Single-wire mode



Chapter 15 Real-Time Counter (S08RTCV1)



When BDM is active, the coherency mechanism is frozen (unless reset by writing to TPMxSC register) such that the buffer latches remain in the state they were in when the BDM became active, even if one or both halves of the modulo register are written while BDM is active. Any write to the modulo registers bypasses the buffer latches and directly writes to the modulo register while BDM is active.



Reset the TPM counter before writing to the TPM modulo registers to avoid confusion about when the first counter overflow will occur.

16.3.4 TPM Channel n Status and Control Register (TPMxCnSC)

TPMxCnSC contains the channel-interrupt-status flag and control bits used to configure the interrupt enable, channel configuration, and pin function.







Timer/PWM Module (S08TPMV3)

Field	Description
7 CHnF	Channel n flag. When channel n is an input-capture channel, this read/write bit is set when an active edge occurs on the channel n pin. When channel n is an output compare or edge-aligned/center-aligned PWM channel, CHnF is set when the value in the TPM counter registers matches the value in the TPM channel n value registers. When channel n is an edge-aligned/center-aligned PWM channel and the duty cycle is set to 0% or 100%, CHnF will not be set even when the value in the TPM counter registers matches the value in the TPM channel n value registers. A corresponding interrupt is requested when CHnF is set and interrupts are enabled (CHnIE = 1). Clear CHnF by reading TPMxCnSC while CHnF is set and then writing a logic 0 to CHnF. If another interrupt request occurs before the clearing sequence is complete, the sequence is reset so CHnF remains set after the clear sequence completed for the earlier CHnF. This is done so a CHnF interrupt request cannot be lost due to clearing a previous CHnF. Reset clears the CHnF bit. Writing a logic 1 to CHnF has no effect. 0 No input capture or output compare event occurred on channel n 1 Input capture or output compare event on channel n
6 CHnIE	 Channel n interrupt enable. This read/write bit enables interrupts from channel n. Reset clears CHnIE. 0 Channel n interrupt requests disabled (use for software polling) 1 Channel n interrupt requests enabled
5 MSnB	Mode select B for TPM channel n. When CPWMS=0, MSnB=1 configures TPM channel n for edge-aligned PWM mode. Refer to the summary of channel mode and setup controls in Table 16-7.
4 MSnA	 Mode select A for TPM channel n. When CPWMS=0 and MSnB=0, MSnA configures TPM channel n for input-capture mode or output compare mode. Refer to Table 16-7 for a summary of channel mode and setup controls. Note: If the associated port pin is not stable for at least two bus clock cycles before changing to input capture mode, it is possible to get an unexpected indication of an edge trigger.
3–2 ELSnB ELSnA	Edge/level select bits. Depending upon the operating mode for the timer channel as set by CPWMS:MSnB:MSnA and shown in Table 16-7, these bits select the polarity of the input edge that triggers an input capture event, select the level that will be driven in response to an output compare match, or select the polarity of the PWM output. Setting ELSnB:ELSnA to 0:0 configures the related timer pin as a general purpose I/O pin not related to any timer functions. This function is typically used to temporarily disable an input capture channel or to make the timer pin available as a general purpose I/O pin when the associated timer channel is set up as a software timer that does not require the use of a pin.

Table 16-6. TPMxCnSC Field Descriptions

Table 16-7. Mode, Edge, and Level Selection

CPWMS	MSnB:MSnA	ELSnB:ELSnA	Mode	Configuration
Х	XX	00	Pin not used for purpose I/O or	TPM - revert to general other peripheral control



Development Support

17.4.1.1 BDC Status and Control Register (BDCSCR)

This register can be read or written by serial BDC commands (READ_STATUS and WRITE_CONTROL) but is not accessible to user programs because it is not located in the normal memory map of the MCU.



= Unimplemented or Reserved

Figure 17-6. BDC Status and Control Register (BDCSCR)

Table 17-2. BDCSCR Register Field Descriptions

Field	Description
7 ENBDM	 Enable BDM (Permit Active Background Mode) — Typically, this bit is written to 1 by the debug host shortly after the beginning of a debug session or whenever the debug host resets the target and remains 1 until a normal reset clears it. 0 BDM cannot be made active (non-intrusive commands still allowed) 1 BDM can be made active to allow active background mode commands
6 BDMACT	Background Mode Active Status — This is a read-only status bit.0BDM not active (user application program running)1BDM active and waiting for serial commands
5 BKPTEN	 BDC Breakpoint Enable — If this bit is clear, the BDC breakpoint is disabled and the FTS (force tag select) control bit and BDCBKPT match register are ignored. 0 BDC breakpoint disabled 1 BDC breakpoint enabled
4 FTS	 Force/Tag Select — When FTS = 1, a breakpoint is requested whenever the CPU address bus matches the BDCBKPT match register. When FTS = 0, a match between the CPU address bus and the BDCBKPT register causes the fetched opcode to be tagged. If this tagged opcode ever reaches the end of the instruction queue, the CPU enters active background mode rather than executing the tagged opcode. 0 Tag opcode at breakpoint address and enter active background mode if CPU attempts to execute that instruction 1 Breakpoint match forces active background mode at next instruction boundary (address need not be an opcode)
3 CLKSW	Select Source for BDC Communications Clock — CLKSW defaults to 0, which selects the alternate BDC clock source. 0 Alternate BDC clock source 1 MCU bus clock



Appendix A Electrical Characteristics

Num	С	Parameter	Symbol	V _{DD} (V)	Typ ¹	Max ²	Unit
		Stop2 mode supply current					
	С	–40°C (C,M, & V suffix)			0.9	_	
	Р	25°C (All parts)			0.9	1	
	P ⁵	85°C (C suffix only)		5	5.0	40.0	μA
	P ⁵	105°C (V suffix only)			11.0	50.0	
5	P ⁵	125°C (M suffix only)	S2I _{DD}		29.1	65.0	
	С	–40°C (C,M, & V suffix)			0.9	-	
	Р	25°C (All parts)			0.9	-	
	P ⁵	85°C (C suffix only)		3	4.2	35.0	μA
	P ⁵	105°C (V suffix only)			8.8	45.0	
	P ⁵	125°C (M suffix only)			25	60.0	
6	С	RTC adder to stop2 or stop3 ⁶	S23I _{DDRTI}	5	300	500	nA
0				3	300	500	nA
7	С	LVD adder to stop3 (LVDE = LVDSE = 1)	S3I _{DDLVD}	5	110	180	μA
,				3	90	160	μA
8	С	Adder to stop3 for oscillator enabled ⁷ (EREFSTEN =1)	S3I _{DDOSC}	5,3	5	8	μA

Table A-7.	Supply	Current	Characteristics ((continued))
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¹ Typical values for specs 1, 2, 3, 6, 7, and 8 are based on characterization data at 25°C. See Figure A-5 through Figure A-7 for typical curves across temperature and voltage.

² Max values in this column apply for the full operating temperature range of the device unless otherwise noted.

³ All modules except ADC active, ICS configured for FBELP, and does not include any dc loads on port pins

⁴ All modules except ADC active, ICS configured for FEI, and does not include any dc loads on port pins

- ⁵ Stop currents are tested in production for 25°C on all parts. Tests at other temperatures depend upon the part number suffix and maturity of the product. Freescale may eliminate a test insertion at a particular temperature from the production test flow once sufficient data has been collectd and is approved.
- ⁶ Most customers are expected to find that auto-wakeup from stop2 or stop3 can be used instead of the higher current wait mode.
- ⁷ Values given under the following conditions: low range operation (RANGE = 0) with a 32.768kHz crystal and low power mode (HGO = 0).





Figure A-7. Typical Stop I_{DD} vs. Temperature (V_{DD} = 5V)

A.8 External Oscillator (XOSC) Characteristics

Table A-8. Oscillator Electrical Specifications
(Temperature Range = -40 to 125°C Ambient)

Num	С	Rating	Symbol	Min	Typ ¹	Max	Unit
		Oscillator crystal or resonator (EREFS = 1, ERCLKEN = 1)					
		Low range (RANGE = 0)	f _{lo}	32	—	38.4	kHz
1	С	High range (RANGE = 1) FEE or FBE mode 2	f _{hi}	1	—	5	MHz
		High range (RANGE = 1, HGO = 1) FBELP mode	f _{hi-hgo}	1	—	16	MHz
		High range (RANGE = 1, HGO = 0) FBELP mode	f _{hi-lp}	1	—	8	MHz
2	_	Load capacitors	C _{1,} C ₂	See crystal or resonator manufacturer's recommendation.			
		Feedback resistor					
3 —	—	Low range (32 kHz to 100 kHz)	R _F	—	10	—	MΩ
		High range (1 MHz to 16 MHz)		—	1	—	
4 —	Series resistor						
	Low range, low gain (RANGE = 0, HGO = 0)		—	0	—		
		Low range, high gain (RANGE = 0, HGO = 1)		—	100	—	
		High range, low gain (RANGE = 1, HGO = 0)	Ba	—	0	—	kO
		High range, high gain (RANGE = 1, HGO = 1)					N22
		≥ 8 MHz		—	0	0	
		4 MHz		—	0	10	
		1 MHz		—	0	20	